# 2SB1417A

## Silicon PNP epitaxial planar type

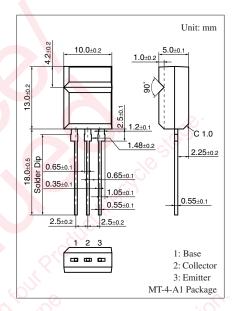
For power amplification Complementary to 2SD2137A

#### ■ Features

- High forward current transfer ratio h<sub>FE</sub> which has satisfactory linearity
- Low collector-emitter saturation voltage V<sub>CE(sat)</sub>
- Allowing automatic insertion with radial taping

### ■ Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol Rating		Unit	
Collector-base voltage (Emitter open)	$V_{CBO}$	-80	V	
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	-80	V	
Emitter-base voltage (Collector open)	$V_{EBO}$	-6	V	
Collector current	$I_{C}$	-3	A	
Peak collector current	$I_{CP}$	-5	A	
Collector power $T_C = 25^{\circ}C$	P <sub>C</sub>	15	W	
dissipation		2.0	(0)	
Junction temperature	$T_{j}$	150	°C	
Storage temperature	T <sub>stg</sub>	<b>−55</b> ~ <b>+150</b>	oc.(	



### ■ Electrical Characteristics T<sub>a</sub> = 25°C ± 3°C

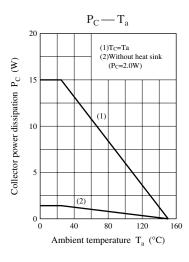
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_C = -30 \text{ mA}, I_B = 0$	-80			V
Base-emitter voltage	$V_{BE}$	$V_{CE} = -4 \text{ V}, I_{C} = -3 \text{ A}$	7.9		-1.8	V
Collector-emitter cutoff current (E-B short)	I <sub>CES</sub>	$V_{CE} = -80 \text{ V}, V_{BE} = 0$			-100	μΑ
Collector-emitter cutoff current (Base open)	$I_{CEO}$	$V_{CE} = -60 \text{ V}, I_B = 0$			-100	μΑ
Emitter-base cutoff current (Collector open)	$I_{EBO}$	$V_{EB} = -6 \text{ V}, I_C = 0$			-100	μΑ
Forward current transfer ratio	h <sub>FE1</sub> *	$V_{CE} = -4 \text{ V}, I_{C} = -1 \text{ A}$	70		250	_
	h <sub>FE2</sub>	$V_{CE} = -4 \text{ V}, I_{C} = -3 \text{ A}$	10			
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = -3 A, I_B = -0.375A$			-1.2	V
Transition frequency	$f_T$	$V_{CE} = -5 \text{ V}, I_C = -0.2 \text{ A}, f = 10 \text{ MHz}$		30		MHz
Turn-on time	t <sub>on</sub>	$I_C = -1 A$ , $I_{B1} = -0.1 A$ , $I_{B2} = 0.1 A$		0.3		μs
Storage time	t <sub>stg</sub>	$V_{CC} = -50 \text{ V}$		1.0		μs
Fall time	t <sub>f</sub>			0.2		μs

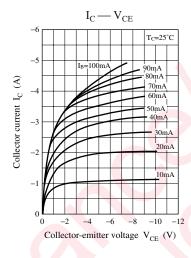
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

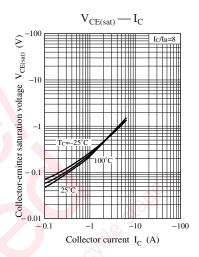
#### 2. \*: Rank classification

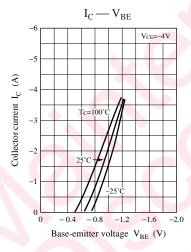
Rank	Q	Р
$h_{\rm FE1}$	70 to 150	120 to 250

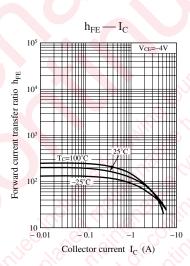
## **Panasonic**

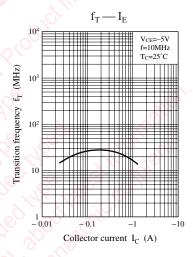


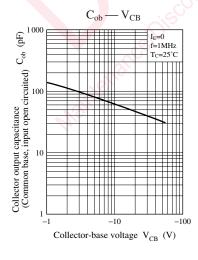


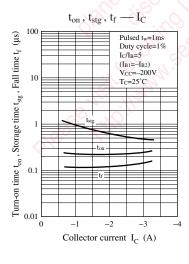


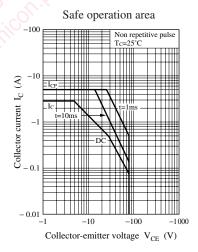




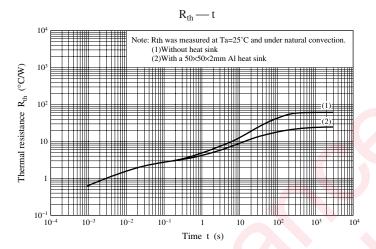








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